



March 22, 2004

To: Commissioner for Patents
P.O.Box 1450
Alexandria, VA 22313-1450

Fr: George O. Saile, Reg. No. 19,572
28 Davis Avenue
Poughkeepsie, N.Y. 12603

Subject: | Serial No. 10/754,835 01/09/04 |
Min-Hsiung Chiang
METHOD TO REDUCE A CAPACITOR
DEPLETION PHENOMENA
| _____ |

INFORMATION DISCLOSURE STATEMENT

Enclosed is Form PTO-1449, Information Disclosure Citation
In An Application.

The following Patents and/or Publications are submitted to
comply with the duty of disclosure under CFR 1.97-1.99 and
37 CFR 1.56.

CERTIFICATE OF MAILING

I hereby certify that this correspondence is being
deposited with the United States Postal Service as first class
mail in an envelope addressed to: Commissioner for Patents,
P.O. Box 1450, Alexandria, VA 22313-1450, on March 25, 2004.

Stephen B. Ackerman, Reg.# 37761

Signature/Date Stephen B. Ackerman 3/25/04


U.S. Patent 6,661,043 to Huang et al., "One-Transistor RAM Approach for High Density Memory Application," discusses a new method for the creation of a 1T RAM cell.

U.S. Patent 6,555,430 to Chudzik et al., "Process Flow for Capacitance Enhancement in a DRAM Trench," discusses methods forming a trench region of a trench capacitor structure having increase surface area.

U.S. Patent 6,420,226 to Chen et al., "Method of Defining a Buried Stack Capacitor Structure for a One Transistor RAM Cell," discloses a process for fabricating a buried stack capacitor structure, to be used in a one transistor, RAM cell.

U.S. Patent Application Publication US 2002/0094697 A1 to Leung et al., "DRAM Cell having a Capacitor Structure Fabricated Partially in a Cavity and Method for Operating Same," discusses a memory system that includes a dynamic random access memory (DRAM) cell including an access transistor and a capacitor structure fabricated in a semiconductor substrate.

Sincerely,

A handwritten signature in black ink, appearing to read 'Stephen B. Ackerman', with a stylized flourish at the end.

Stephen B. Ackerman,
Reg. No. 37761

